

AMENDMENTS TO THE SPECIFICATION AND ABSTRACT:

Please replace paragraph [0043] of the substitute specification with the following paragraph:

[0043] Fig. 12 is a perspective view of a region 69 for the signal electrode 65. The region 69 consists of a land 70 mounted on upper and lower sides of the substrate 62. Upon having the signal electrodes 65 connected at a lower side of the substrate, the module can reduce an overall size of a device including the module mounted thereto.

Please replace paragraph [0044] of the substitute specification with the following paragraph:

[0044] Fig. 13 illustrates ~~a substrate 62~~ an internal layer 162 of the substrate 62 of this embodiment having a multi-layer construction. As shown, the substrate 62 includes ~~an~~ the internal layer ~~72~~ 162 in a printed mother board, a worksheet form, before being separated into substrates 62. A pattern 72 on the internal layer ~~72~~ 162 of the substrate 62 is connected to a land 73 connected to region 69 for a signal electrode 65 with a through hole. The signal electrode 65 is separated along a cut line 63. The cut line 63 is spaced by a distance 74 from the land 73. The distance 74 allows the substrates 62 in the worksheet form to be inspected prior to separation. That is, signal electrodes 65 of any two adjacent substrates 62 in the worksheet form are electrically isolated from each other, and thus, signals to them can be separated without a dummy substrate.

Please add the following paragraph beginning at page 13, line 3, of the substitute specification with the following paragraph:

[0059] In each of the above embodiments, because the mother board is cut through portions of the interior surface of the hole from which metal plating has been removed, the resulting substrate will have a surface, defined by the cut, with which no portion of an electrode (the metal plating within the hole) is co-planar.